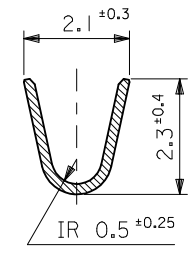
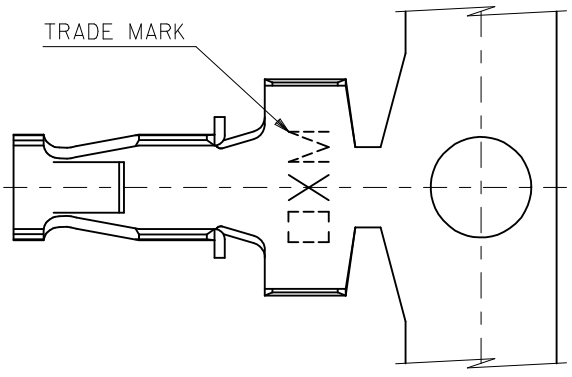
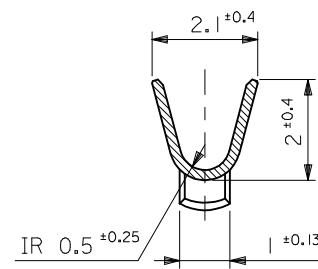


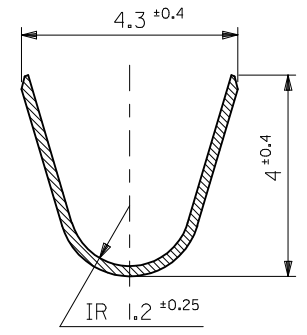
TRADE MARK



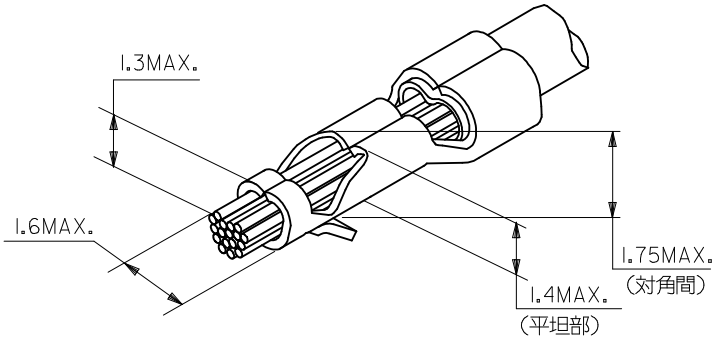
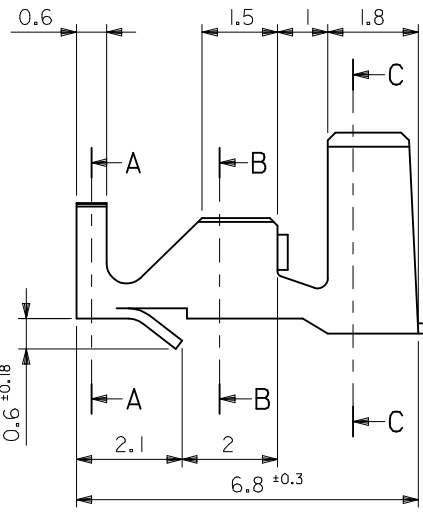
SECT. A-A



SECT. B-B



SECT. C-C



压着外觀図
OUTSIDE VIEW OF CRIMP

NOTES

- 推奨プリント基板孔径: $\phi 1.8^{+0.1}$
RECOMMENDED P.C.B. HOLES: $\phi 1.8^{+0.1}$
- 推奨プリント基板厚: $t1.57^{+0.2}$
RECOMMENDED P.C.B. THICKNESS: $1.57^{+0.2}$
- 材料の厚み: 0.203
MATERIAL THICKNESS: 0.203

| | | | | |
|--|-----------------|----------|------------|----------|
| TIN-LEAD(90-10) 3.8 μ m MIN. OVER NICKEL 1.3 μ m MIN. | PHOSPHOR BRONZE | CHAIN | 39-00-0277 | 5298PBPT |
| TIN 0.9 μ m MIN. REFLOW TREATMENT (PRE-PLATED) | PHOSPHOR BRONZE | CHAIN | 39-00-0230 | 5298PBT |
| TIN 0.9 μ m MIN. OVER COPPER 0.5 μ m MIN. (PRE-PLATED) | BRASS | CHAIN | 08-70-0106 | 5298T |
| PLATING | | MATERIAL | FORM | EDP NO. |
| | | | | ENG. NO. |

| | |
|----------------------|------------------|
| 材料 MATERIAL | SEE TABLE & NOTE |
| 仕上げ FINISH | — |
| 適用電線範囲 WIRE RANGE | AWG #18-22 |
| 被覆外径 INS. RANGE | $\phi 1.7-3.05$ |

| | | |
|---|--|-------|
| REVISED EC NO: J2017-0224 DRAWN: SHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MASAO 2016/10/14 | GENERAL TOLERANCES (UNLESS SPECIFIED) | ± |
| | 0.25 UNDER | ± |
| | 0.25 OVER 0.5 UNDER | ± |
| | 0.5 OVER 1.0 UNDER | ± |
| | 10 OVER 30 UNDER | ±0.25 |
| 30 OVER | ±0.3 | |
| ANGULAR | ±3 ° | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | |

| | |
|----------------------------|-------------------|
| DIMENSION STYLE MM ONLY | |
| DRAWN BY H.HIRAMOTO | DATE '91/09/05 |
| CHECKED BY | DATE |
| H.HIRAMOTO | '93/07/06 |
| APPROVED BY M.FUKUSHIMA | DATE '93/07/06 |
| MATERIAL NO. | |
| SEE TABLE | |

| | | |
|---|------------------------|---------------------------|
| SCALE | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| TITLE LOW PROFILE PC BOARD CRIMP PIN | | |
| molex | | |
| DOCUMENT NO. SD-5298-001 | SHEET NO. 1 OF 1 | |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |